Power Transistors Panasonic

2SC1953

Silicon NPN epitaxial planar type

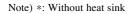
For low-frequency power pre-amplification Complementary to 2SA0914

■ Features

- \bullet High collector to emitter voltage V_{CEO}
- Small collector output capacitance C_{ob}
- A complementary pair with 2SA0914, is optimum for the pre-driver stage of a 60 W to 100 W output amplifier
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	150	V
Collector to emitter voltage	V_{CEO}	150	V
Emitter to base voltage	V_{EBO}	5	V
Peak collector current	I_{CP}	100	mA
Collector current	I_C	50	mA
Collector power dissipation *	P_{C}	1.2	W
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C



Unit: mm 8.0^{+0.5} 9.3.16±0.1 0.75±0.1 0.5±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1 1.76±0.1

■ Electrical Characteristics $T_C = 25$ °C

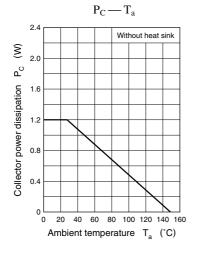
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 100 \text{ V}, I_{E} = 0$			1	μΑ
Collector to emitter voltage	V _{CEO}	$I_C = 100 \ \mu A, I_B = 0$	150			V
Emitter to base voltage	V_{EBO}	$I_{\rm E} = 10 \; \mu A, \; I_{\rm C} = 0$	5			V
Forward current transfer ratio *	h _{FE}	$V_{CE} = -5 \text{ V}, I_{C} = 10 \text{ mA}$	130		330	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 30 \text{ mA}, I_B = 3 \text{ mA}$			1	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$	70			MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			3	pF

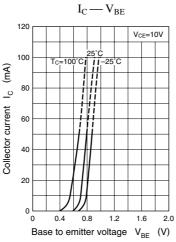
Note) *: Rank classification

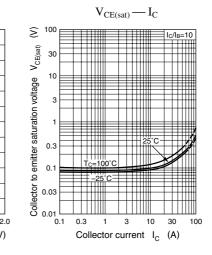
Rank	Q	R
h_{FE}	130 to 220	185 to 330

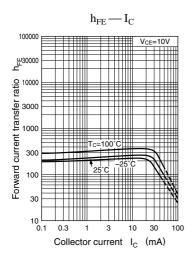
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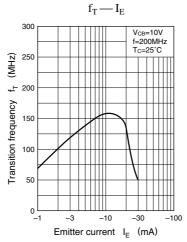
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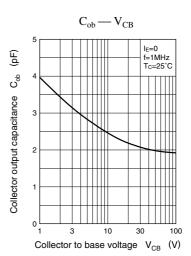












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